



News Release

FOR IMMEDIATE RELEASE

Elpida Announces Organizational and Personnel Changes

TOKYO, JAPAN, August 26, 2008 – Elpida Memory has announced the following changes to its company organizational structure and to personnel that will take effect on August 27.

1. Organizational Change: Business Units to be Established

A DRAM Business Unit and a New Business Unit will be established to reorganize and better unite Offices and Divisions related to DRAM and new business operations.

Background:

In addition to further strengthening Elpida's core DRAM business, the expansion of the company's Foundry Business has assumed an important role in stabilizing overall business performance. Also, with such new technology as next-generation memory and one-chip solution TSV* technology expected to come into use over the next several years, Elpida recognizes these technologies as a significant source of important new business.

Given these circumstances Elpida has created the DRAM Business and New Business Unit to accelerate relevant decision-making processes and further strengthen the market competitiveness of each of its business.

2. Personnel Changes: Adjustment of Director Responsibilities

The following changes in director responsibilities will take place in line with the creation of the new business units.

* TSV: Through Silicon Via is three-dimensional stack packaging technology. The technology involves plugging up small holes open on the chip die with metal electrodes to electronically connect multiple chips together in a sandwich style. Compared with the existing connection method of wire bonding multiple chips, TSV drastically reduces the wire distance, which enables faster speeds, lower power consumption, smaller package size and other important advantages.

Elpida is now working on developing technology that would enable high-speed operations by stacking together multiple DRAM chips and a controller chip and connecting them with TSV technology.

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Name	New Position	Current Position
Shuichi Otsuka	<ul style="list-style-type: none">– Director– Chief Operating Officer (COO)– <u>Head of DRAM Business Unit</u>– Responsible for the Sales Office	<ul style="list-style-type: none">– Director– Chief Operating Officer (COO)– Responsible for the Sales Office
Takao Adachi	<ul style="list-style-type: none">– Director– <u>Head of New Business Unit</u>– Responsible for the Future Technology Development Office (CTO of New Business Unit), <u>Foundry Business Div.</u>, Quality Assurance & the Corporate Communications Group	<ul style="list-style-type: none">– Director– Responsible for the Future Technology Development Office (Co-CTO), Business Development Office, Quality Assurance & the Corporate Communications Group

About Elpida

Elpida Memory, Inc. (Tokyo: 6665) is a leading manufacturer of Dynamic Random Access Memory (DRAM) integrated circuits. The company's design, manufacturing and sales operations are backed by world class technological expertise. Its 300mm manufacturing facilities, consisting of its Hiroshima Plant and a Taiwan-based joint venture, Rexchip Electronics, utilize the most advanced manufacturing technologies available. Elpida's portfolio features such characteristics as high-density, high-speed, low power and small packaging profiles. The company provides DRAM solutions across a wide range of applications, including high-end servers, mobile phones and digital consumer electronics. More information can be found at <http://www.elpida.com>.

Information in this news release is current as of the timing of the release, but may be revised later without notice.

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